

REMARKS

The foregoing Amendment and Remarks which follow are responsive to the Office Action mailed March 7, 2006 in relation to the above-identified patent application. In that Office Action, the Examiner rejected Claims 1-5, 7-15 and 17-19 under 35 U.S.C. §102(e) as purportedly being anticipated by the Miks et al. reference (US 2005/0030723 A1). Additionally, the Examiner rejected Claims 6 and 16 under 35 U.S.C. §103(a) as being unpatentable over the combination of the Miks et al. reference in view of the Lo et al. reference (US 5,617,297).

By this Amendment, Applicant has amended independent Claim 1 to describe the second encapsulation in part of the memory card as “*being separate from the first encapsulation part.*” Applicant respectfully submits that this particular change to independent Claim 1 does not add an additional substantive element thereto, but serves only to clarify that the first and second encapsulation parts of the memory card are separate and distinct components, as opposed to comprising portions of a unitary structure. Applicant has also added new independent Claim 20 into prosecution.

Independent Claims 1 and 11 are Not Anticipated by the Miks et al. Reference

Applicant respectfully submits that neither independent Claim 1 as amended or independent Claim 11 in its original form is anticipated by the Miks et al. reference. The Miks et al. reference discloses a memory card comprising a substrate assembly 10, 10A. The substrate assembly 10, 10A itself comprises a substrate 11, 11A, 11B having integrated circuit dies 13 attached to the top side thereof, and contacts 14 on the bottom side thereof. Conductive patterns within the substrate 11, 11A, 11B are used to electrically connect the integrated circuit dies 13 to the contacts 14. In the substrate assembly 10, 10A shown in Figures 1A and 1B, respectively, the integrated circuit dies 13 and portions of only the top side of the substrate 11, 11A are covered by an inner encapsulant 12, 12A. The inner encapsulant 12, 12A, while covering the integrated circuit dies 13 and portions of the top side of the substrate 11, 11A, does not cover the bottom side thereof. As described in the Miks et al. reference, such inner encapsulant 12, 12A is ultimately covered by a lid or similar cover

which is attached thereto through the use of an adhesive to provide a suitable exterior housing for the memory card.

In an alternative embodiment of the memory card shown in Figure 2A, the integrated circuit dies 13, the top side of the substrate 11B, and the bottom side of the substrate 11B except for the contacts 14 are covered by a *unitary* housing 20A. In Paragraph [0026] of the Miks et al. reference, the housing 20A is specifically described as being “*molded around substrate 11B on all sides...*” Thus, with regard to the fully-molded version of the circuit module 30 shown in Figure 2A of the Miks et al. reference, the disclosure is limited to a single, unitary housing 20A which covers both the top and bottom sides of the substrate 11B, as well as the integrated circuit dies 13 attached to the top side of the substrate 11B.

In contrast, in independent Claim 1 as amended, the memory card is described as having a first encapsulation part which is formed on the bottom surface of the substrate, and a second encapsulation part which is formed on the top surface of the substrate and encapsulates the component mounted thereto, *the second encapsulation part being separate from the first encapsulation part*. Similarly, independent Claim 11 in its original form recites the separate steps of forming a first encapsulation part on the bottom surface of the substrate, and thereafter forming a second encapsulation part on the top surface of the substrate in a manner encapsulating the component mounted thereto. Thus, each of independent Claims 1 and 11 contemplates the existence or formation of two separate and distinct encapsulation parts, namely the first encapsulation part which is formed to cover the bottom surface of the substrate and the second encapsulation part which is formed to cover the top surface of the substrate as well as the component mounted thereto. Applicant respectfully submits that these particular features are simply not taught or suggested by the Miks et al. reference, the disclosure of which is limited to the single, unitary housing 20A as described above.

Thus, Applicant respectfully submits that independent Claims 1 and 11 are not anticipated by the Miks et al. reference, and are condition for allowance. Additionally, Applicant respectfully submits that Claims 2-10 and 12-19 are also in condition for allowance as being dependent upon respective allowable base claims.

New Independent Claim 20 is Not Anticipated by the Miks et al. Reference

New independent Claim 20 is similar to independent Claim 11, and describes the method for fabricating the memory card as including the separate steps of applying a mold compound to the bottom surface of the substrate, and thereafter applying a mold compound to the top surface of the substrate in a manner encapsulating the component mounted thereto. Thus, for the same reasons set forth above in relation to independent Claim 11, Applicant respectfully submits that new Claim 20 is also not anticipated by the Miks et al. reference, and is in condition for allowance.

Conclusion

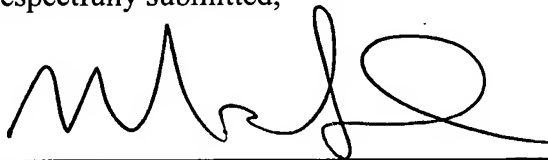
On the basis of the foregoing, Applicant respectfully submits that the stated grounds of rejection have been overcome, and that Claims 1-20 are now in condition for allowance. An early Notice of Allowance is therefore respectfully requested.

If any additional fee is required, please charge Deposit Account Number 19-4330.

Respectfully submitted,

Date: 6/5/06

By:



Customer No.: 007663

Mark B. Garred
Registration No. 34,823
STETINA BRUNDA GARRED & BRUCKER
75 Enterprise, Suite 250
Aliso Viejo, California 92656
Telephone: (949) 855-1246
Fax: (949) 855-6371